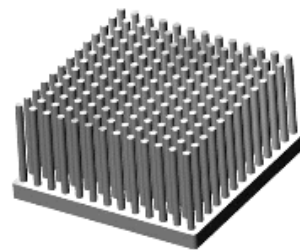


Product- information Type: PB5050/25/SE/SF

Group: Special heatsinks, Finger shaped heatsinks

Heatsinks for Microprocessors (PGA, BGA, IC)

Application (Cases):	PGA, BGA, IC
Number of semiconductors:	1
Mounting of semiconductors :	to glue
Mounting of heatsinks:	to glue
Finish:	black anodized
Thermal resistance:	3.7 K/W
Material:	AL 99,5



Heatsinks for microprocessors

- Direct mounting with highly thermally conductive self-adhesive foil
- Best possible heat radiation from black anodized surface
- Other dimensions and surface finishes by request
- RthKvalues apply to natural convection (without external ventilation)

Made from pure aluminium (Al 99,5-thermal conductivity 210-236 W/mK)

(Cold forging technology)

- further improved thermal conductivity due to high material density.

